SN54ABT2953 ... JT PACKAGE

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- State-of-the-Art *EPIC-*II*B* ™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Two 8-Bit, Back-to-Back Registers Store Data Flowing in Both Directions
- Inverting Outputs
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Standard Plastic and Ceramic 300-mil DIPs (JT, NT)

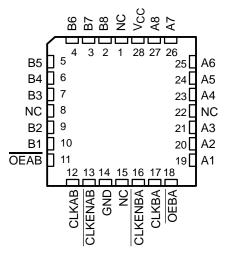
#### description

The 'ABT2953 consists of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN74ABT2953 DB, DW, OR NT PACKAGE (TOP VIEW)										
B8 [		24	V <sub>CC</sub>							
B7 [	2	23	A8							
B6 [	3	22	A7							
B5 [	4	21	A6							
B4 [	5	20	A5							
B3 [	6	19	A4							
B2 [	7	18	A3							
B1 [	8	17	A2							
OEAB	9	16	A1							
CLKAB	10	15	OEBA							
CLKENAB	11	14	CLKBA							
GND 🛛	12	13	CLKENBA							

#### SN54ABT2953 ... FK PACKAGE (TOP VIEW)



NC – No internal connection

The SN74ABT2953 is packaged in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT2953 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT2953 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

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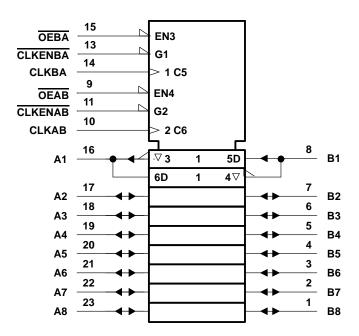
FUNCTION TABLE <sup>†</sup>									
	OUTPUT								
CLKENAB	В								
н	Х	L	Х	в <sub>0</sub> ‡					
Х	H or L	L	Х	в <sub>0</sub> ‡ в <sub>0</sub> ‡					
L	$\uparrow$	L	L	н					
L	$\uparrow$	L	Н	L					
Х	Х	Н	Х	Z					

.

<sup>†</sup> A-to-B data flow is shown; B-to-A data flow is similar but uses CLKENBA, CLKBA, and OEBA.

<sup>‡</sup>Level of B before the indicated steady-state input conditions were established.

### logic symbol§

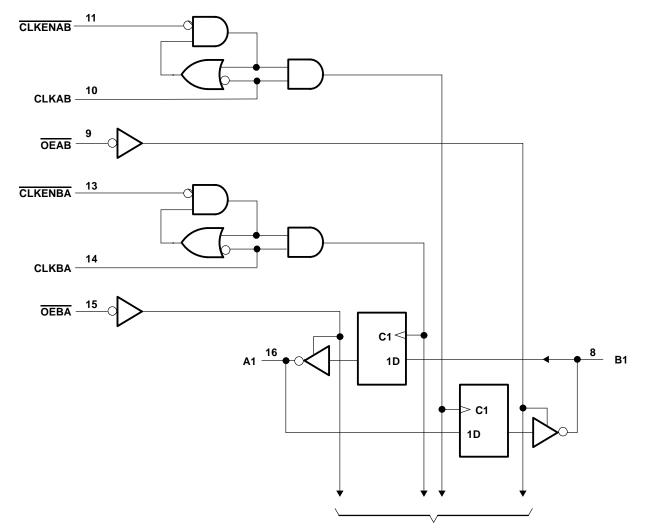


 $\$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, and NT packages.



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# SN54ABT2953, SN74ABT2953 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SCBS467 – FEBRUARY 1991 – REVISED OCTOBER 1992



Pin numbers shown are for DB, DW, JT, and NT packages.

logic diagram (positive logic)

**To Seven Other Channels** 



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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1) Voltage range applied to any output in the high state or power-off state, V <sub>O</sub> Current into any output in the low state, I <sub>O</sub> : SN54ABT2953	−0.5 V to 7 V −0.5 V to 5.5 V
SN74ABT2953	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air): DB package	0.7 W
DW package	
NT package	
Storage temperature range	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

#### recommended operating conditions (see Note 2)

			SN54AB	T2953	SN74AB		
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
$V_{ L}$	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0	VCC	0	VCC	V
ЮН	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.



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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			٦	[A = 25°	C	SN54ABT2953		SN74ABT2953		
PARAMETER				MIN	түр†	MAX	MIN	MAX	MIN	MAX	UNIT
VIK	V <sub>CC</sub> = 4.5 V,	$V_{CC} = 4.5 V$ , $I_{I} = -18 mA$				-1.2		-1.2		-1.2	V
	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = - 3 m/	A	2.5			2.5		2.5		
VOH	V <sub>CC</sub> = 5 V,	I <sub>OH</sub> = – 3 mA	A	3			3		3		.,
		I <sub>OH</sub> = -24 m	A	2			2				V
	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = - 32 m	2‡					2			
		I <sub>OL</sub> = 48 mA				0.55		0.55			V
VOL	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA				0.55‡				0.55	v
łı	$V_{CC} = 5.5 V,$ $V_{I} = V_{CC} \text{ or GND}$		Control inputs			±1		±1		±1	μΑ
			A or B ports			±100		±100		±100	
IOZH§	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V					50		50		50	μA
IOZL <sup>§</sup>	V <sub>CC</sub> = 5.5 V,					-50		-50		-50	μA
l <sub>off</sub>	V <sub>CC</sub> = 0,	$V_{I} \text{ or } V_{O} \leq 4.$	5 V			±100				±100	μΑ
ICEX	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
۱ <sub>0</sub> ¶	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	•	-50	-100	-180	-50	-180	-50	-180	mA
	V <sub>CC</sub> = 5.5 V,	A or B ports	Outputs high		1	250		250		250	μΑ
ICC			Outputs low		24	35		35		35	mA
			Outputs disabled		0.5	250		250		250	μΑ
∆I <sub>CC</sub> #	$V_{CC} = 5.5 \text{ V}$ , One input at 3.4 V, Other inputs at $V_{CC}$ or GND				1.5		1.5		1.5	mA	
Ci	VI = 2.5 V or 0.5 V Control inputs				4						pF
Cio	V <sub>O</sub> = 2.5 V or 0.5 V	/	A or B ports		7						pF

<sup>†</sup> All typical values are at  $V_{CC} = 5$  V.

<sup>‡</sup>On products compliant to MIL-STD-883, Class B, this parameter does not apply.

The parameters IOZH and IOZL include the input leakage current.
Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

#### timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				V <sub>CC</sub> =	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT2953		SN74ABT2953	
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			0	150	0	150	0	150	MHz
	Pulse duration		CLK high	3		3		3		
١w	t <sub>W</sub> Pulse duration		CLK low	3.5		3.5		3.5		ns
		A or B	High	4		4		4		
	Satur time before CLK <sup>↑</sup>	AUB	Low	3		3		3		
lsu	t <sub>SU</sub> Setup time before CLK <sup>↑</sup>		High	3.5		3.5		3.5		ns
		CLKEN	Low	2.5		2.5		2.5		
th Hold time after CLI		A or B		0		0		0		
		CLKEN		0		0		0		ns



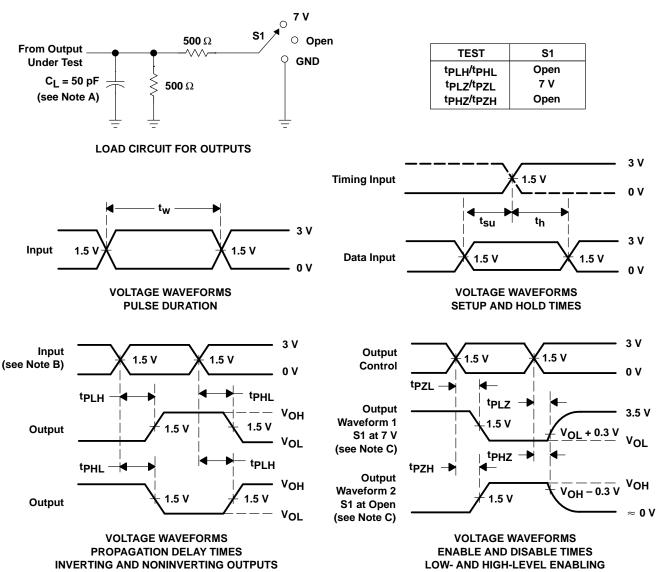
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT2953		SN74ABT2953		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
fmax			150			150		150		MHz
<sup>t</sup> PLH	CLKBA or CLKAB	A or CLKAB A or B	2.6	5.1	6.6	2.6		2.6	7.6	ns
<sup>t</sup> PHL			3.2	5.7	7.2	3.2		3.2	8.2	
<sup>t</sup> PZH	OEBA or OEAB	A or B	1	3.3	4.8	1		1	5.8	ns
<sup>t</sup> PZL		AUB	2.2	4.7	6.2	2.2		2.2	7.5	115
<sup>t</sup> PHZ	OEBA or OEAB	A or B	3.6	6.1	7.6	3.6		3.6	8.1	200
<sup>t</sup> PLZ		AUB	3.1	6.6	7.1	3.1		3.1	7.6	ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.

C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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